



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISC060N10NM6	Issued	08. February 2022
MA#	MA005428577		
Package	PG-TDSON-8-26	Weight*	115.21 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.976	0.85	0.85	8474	8474
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.049	0.04		424	
	non noble metal	copper	7440-50-8	48.769	42.35	42.40	423316	423867
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	392	392
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		724	
	plastics	epoxy resin	-	6.592	5.72		57221	
	inorganic material	silicondioxide	60676-86-0	35.047	30.42	36.21	304210	362155
leadfinish	non noble metal	tin	7440-31-5	1.392	1.21	1.21	12079	12079
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1682	1682
solder	non noble metal	tin	7440-31-5	0.026	0.02		222	
	noble metal	silver	7440-22-4	0.032	0.03		278	
	non noble metal	lead	7439-92-1	1.223	1.06	1.11	10614	11114
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	noble metal	silver	7440-22-4	0.635	0.55		5516	
	non noble metal	copper	7440-50-8	17.131	14.87	15.43	148701	154411
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			26	
	non noble metal	copper	7440-50-8	2.971	2.58	2.58	25792	25826
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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